

Product Change Notification - KSRA-06BENA698

Date: 10 Aug 2017
Product Category: Linear Op Amps
Notification subject: CCB 3054 Initial Notice: Qualification of palladium coated copper with gold flash(CuPdAu) bond wire in selected products of the 130K wafer technology available in 16L QFN package at NSEB assembly site
Notification text: **PCN Status:**
 Initial notification

Microchip Parts Affected:

Please open the attachments found in the attachments field below labeled as PCN_#_Affected_CPN.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

Description of Change:

Qualification of palladium coated copper with gold flash (CuPdAu) bond wire in selected products of the 130K wafer technology available in 16L QFN package at NSEB assembly site

Pre Change:

Using gold (Au) bond wire and EFTEC-64T lead frame material

Post Change:

Using palladium coated copper with gold flash (CuPdAu) bond wire and C194 lead frame material

Pre and Post Change Summary:

	Pre Change	Post Change
Assembly Site	NSEB Assembly Site	NSEB Assembly Site
Wire material	Au Wire	CuPdAu Wire
Die attach material	8600	8600
Molding compound material	G700LTD	G700LTD
Lead frame material	EFTEC-64T	C194

Impacts to Data Sheet:

None

Change Impact:

None

Reason for Change:

To improve manufacturability by qualifying CuPdAu bond wire at NSEB assembly site.

Change Implementation Status:

In Progress

Estimated Qualification Completion Date:

January 2018

Note: Please be advised the qualification completion times may be extended because of unforeseen business conditions however implementation will not occur until after qualification has completed and a final PCN has been issued. The final PCN will include the qualification report and estimated first ship date. Also note that after the estimated first ship date guided in the final PCN customers may receive pre and post change parts.

Time Table Summary:

Workweek	August 2017					-->	January 2018				
	31	32	33	34	35		01	02	03	04	05
Initial PCN Issue Date		X									
Qual Report Availability								X			
Final PCN Issue Date								X			

Method to Identify Change:

Traceability code

Qualification Plan:

Please open the attachments included with this PCN labeled as PCN_#_Qual Plan

Revision History:

August 10, 2017: Issued initial notification.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachment(s):

- [PCN_KSRA-06BENA698_Affected CPN.pdf](#)
- [PCN_KSRA-06BENA698_Qual Plan.pdf](#)
- [PCN_KSRA-06BENA698_Affected CPN.xlsx](#)

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

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Affected Catalog Part Numbers (CPN)

PCN_KSRA-06BENA698
CATALOG_PART_NBR
MCP629-E/ML
MCP629T-E/ML
MCP639-E/ML
MCP639T-E/ML
MCP659-E/ML
MCP659T-E/ML
MCP660-E/ML
MCP660T-E/ML
MCP669-E/ML
MCP669T-E/ML